**NOTES:**
2. CONTROLLING DIMENSION: MILLIMETERS.
3. MAXIMUM LEAD THICKNESS INCLUDES LEAD FINISH.
   MINIMUM LEAD THICKNESS IS THE MINIMUM THICKNESS OF THE BASE MATERIAL.
4. DIMENSIONS D AND E DO NOT INCLUDE MOLD FLASH, PROTRUSIONS, OR GATE BURRS.

**RECOMMENDED SOLDERING FOOTPRINT**

**MECHANICAL CASE OUTLINE**

**PACKAGE DIMENSIONS**

**DOCUMENT NUMBER:** 98ASB42226B

**DESCRIPTION:** SOT–23 (TO–236)

**ON Semiconductor**

SEE VIEW C

**TOP VIEW**

**SIDE VIEW**

**END VIEW**

**VIEW C**

**GENERIC MARKING DIAGRAM**

XXX = Specific Device Code

M = Date Code

* = Pb–Free Package

*This information is generic. Please refer to device data sheet for actual part marking. Pb–Free indicator, "G" or microdot "**, may or may not be present.